

COMMENTS

The enclosed is responsive to the Examiner's Office Action mailed on June 30, 2004. At the time the Examiner mailed the office action claims 1 through 19 were pending. By way of the present response the Applicant has: 1) amended claims 1-6, 11-14 and 19; 2) canceled claims 7-9 and 15-17; and, 3) added claims 20-32. As such claims 1-6, 10-14 and 18-32 are now pending. The Applicants respectfully request reconsideration of the present application and the allowance of all claims.

The Examiner rejected claims 8 and 9 under 35 USC §112, para. 2. See, Examiner's Office Action mailed 6/30/04, pg. 2. The Applicant has herewith canceled claims 8 and 9 thereby rendering the Examiner's rejection moot.

The Examiner rejected independent claims 1, 11 and 19 as being unpatentable over US Patent No. 6,743,671 B2 (hereinafter, "Hu") under 35 USC §102(e). In response the Applicant has amended claims 1 and 19 to additionally recite

- c) a third metal structure at another metal level other than said metal level and other than said lower metal level, said third metal structure at least partially vertically aligned with at least one of said pairs of vertically aligned strips, said third metal structure electrically connected to said inner node; and,
- d) a fourth metal structure at said another metal level, said fourth metal structure substantially surrounding said third metal structure on three sides of said third metal structure within the plane of said another metal level to shield said third metal structure, said fourth metal structure electrically connected to said outer node, said fourth metal structure not completely surrounding said third metal structure within the plane of said another metal level

and has amended claim 11 to recite (emphasis added)

[a] semiconductor chip, comprising:
a capacitive structure comprising, at a same metal level, an outer metal structure that forms a window that surrounds and is isolated from an inner, metal strip within the plane of said metal level, said capacitive structure also comprising, at another metal level, another metal structure that substantially surrounds but does not completely surround an inner metal structure, said another metal structure electrically coupled to said outer metal structure with one or more vias, said inner metal structure electrically coupled to said inner metal strip with one or more vias.

The Examiner is referred to items 203 and 204 of Figure 2a, Figure 2e and Figure 2f as examples of structures covered by the claim language emphasized above with respect to claims 1, 11 and 19.

In light of these amendments the Applicant respectfully submits that the Examiner's rejection has been overcome and respectfully requests the allowance of all claims.

The Applicant's silence to the dependent claims should not be construed as an admission by the Applicant that the Applicant is complicit with the Examiner's rejection of these claims. Because the Applicant has demonstrated the patentability of the independent claims, the Applicant need not substantively address the theories of rejection applied to the dependent claims.

If there are any additional charges, please charge Deposit Account No. 02-2666.

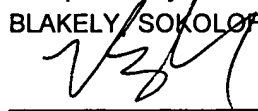
If a telephone interview would in any way expedite the prosecution of this application, the Examiner is invited to contact Robert O'Rourke at (408) 720-8300.

Date:

10/28/04

12400 Wilshire Boulevard
Seventh Floor
Los Angeles, CA 90025-1026
(408) 720-8300

Respectfully submitted,
BLAKELY/SOKOLOFF, TAYLOR & ZAFMAN LLP



Robert B. O'Rourke
Registration Number: 46,972